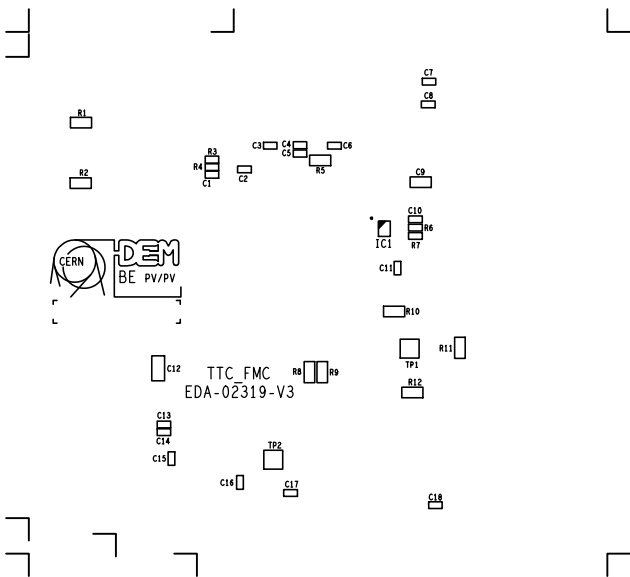


EDA-02319-V3	
DESS	P. VULLIEZ
DATE	13/07/2012

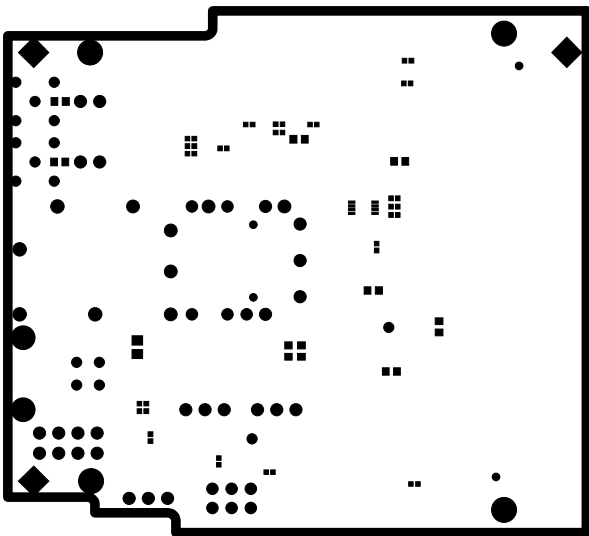
TE/MPE



TE/MPE

EDA-02319-V3	
DESS	P. VULLIEZ
DATE	13/07/2012

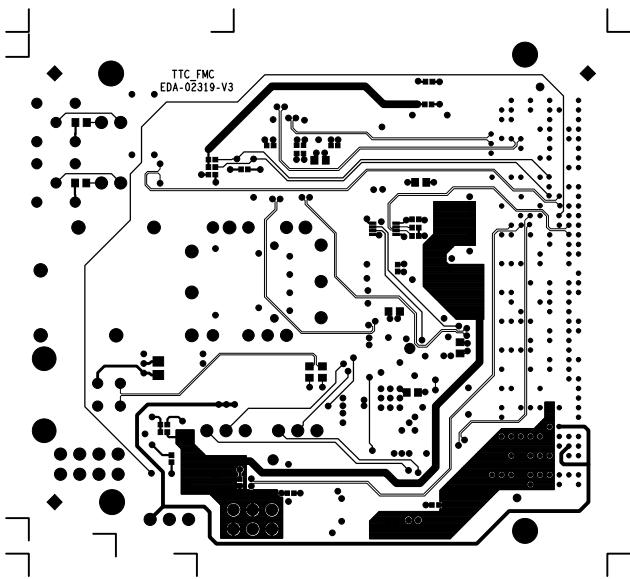
TOP SILKSCREEN



TE/MPE

EDA-02319-V3	
DESS	P. VULLIEZ
DATE	13/07/2012

TOP SOLDERMASK

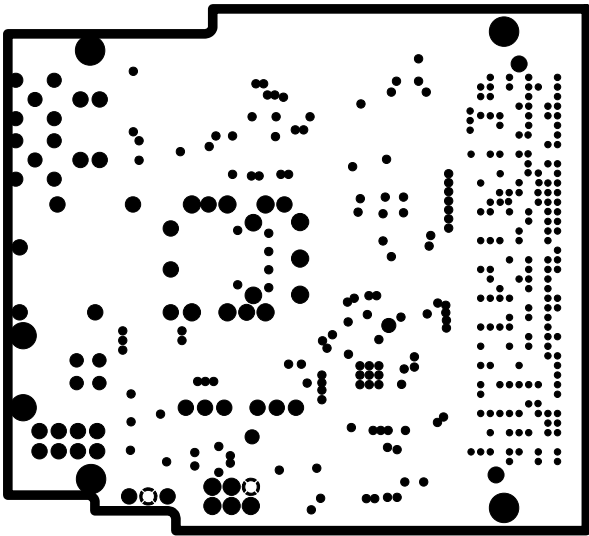


TE/MPE

EDA-02319-V3	
DESS	P. VULLIEZ
DATE	13/07/2012

TOP SIDE

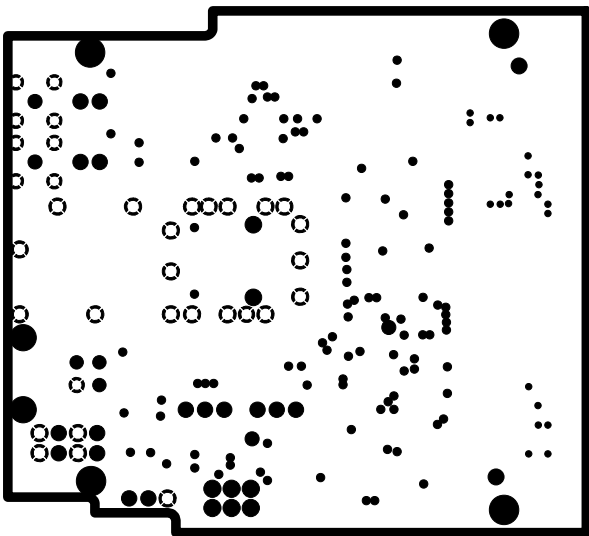
1			
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EDA-02310-V3	DESS P. VULLIETZ
DATE 13\07\2015	TEMPERATURE



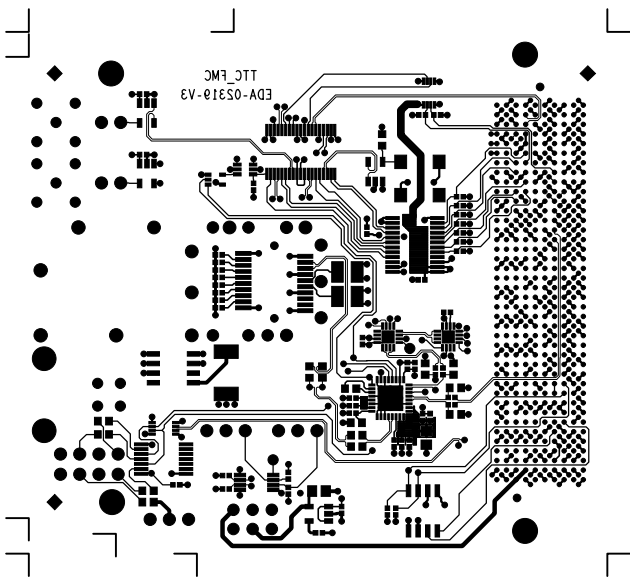
POWER PLANE	2		
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TE/MPE

EDA-02319-V3	
DESS	P. VULLIEZ
DATE	13/07/2012

GROUND PLANE	
	3

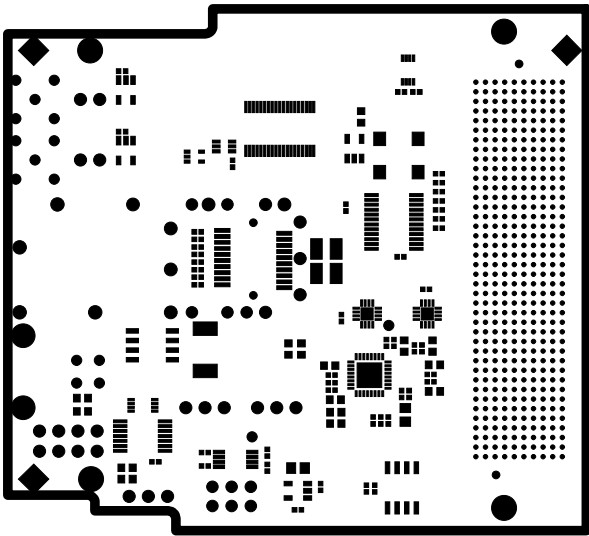


EDB-05310-V3	DATE
DESIGNER P. VULLIETZ	13/07/2015



4

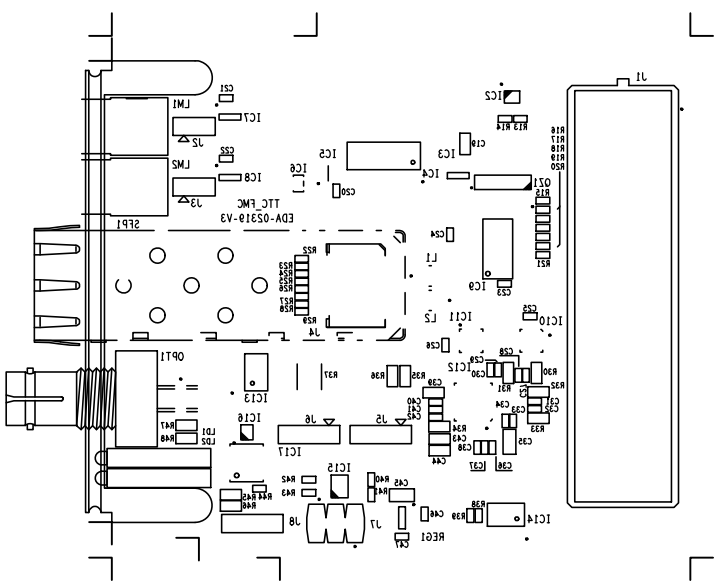
BOTTOM SIDE




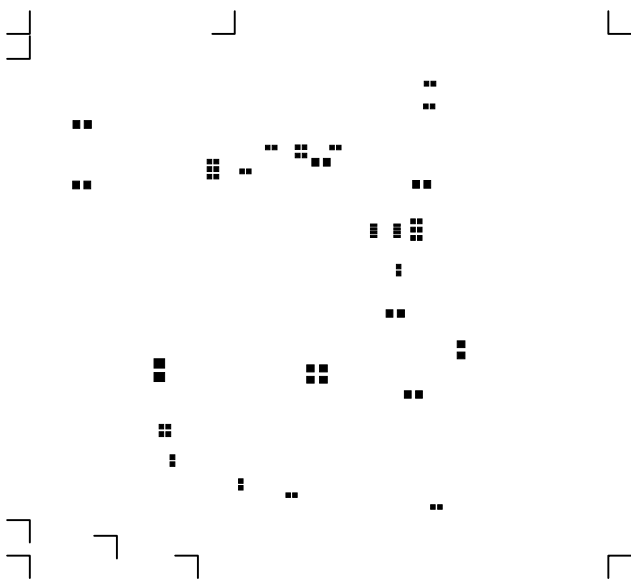
EDA-02310-V3	DESIGNER
DATE	P. VULLIETZ
13/07/2015	



BOTTOM SOLDERMASK



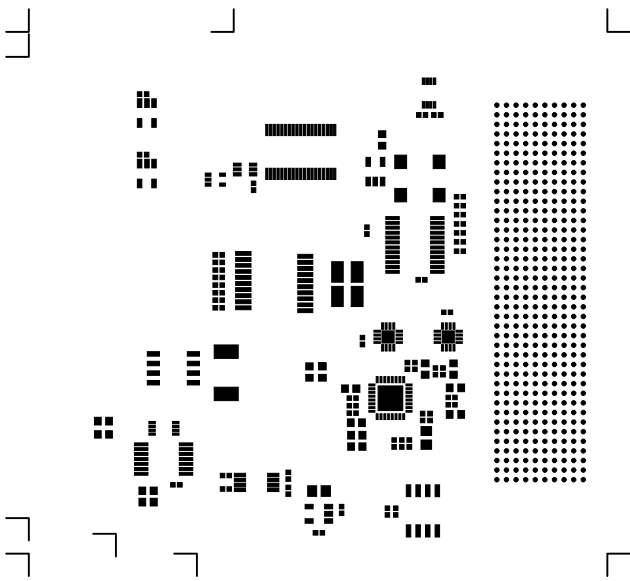
DATE	13\07\2015		BOTTOM SILKSCREEN
DESIGNER	P. VULLIETZ		
EDA-05310-V3			



TE/MPE

EDA-02319-V3	
DESS	P. VULLIEZ
DATE	13/07/2012

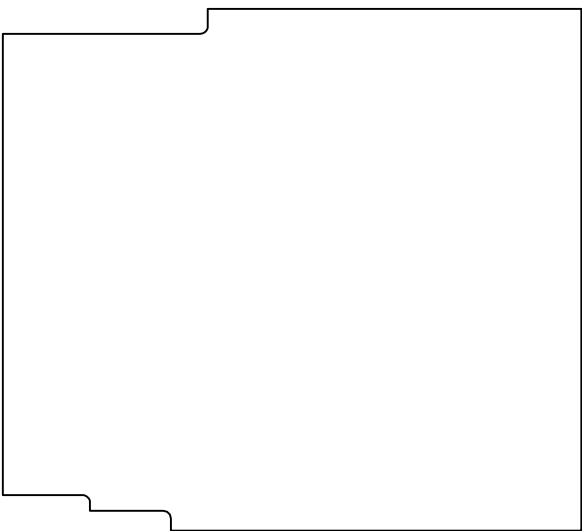
TOP PASTEMASK



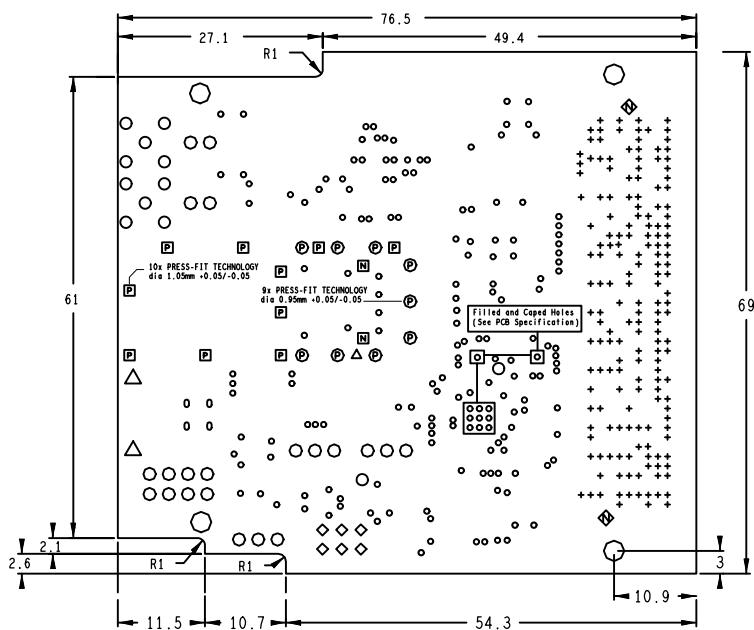
EDA-02310-V3	DESIGNER
DATE 13/07/2015	P. VULLIETZ



BOTTOM PASTEMASK



LAYER IDENTIFICATION		LINE WIDTH/SPACE (mm)	FINISHED COPPER THICKNESS	IMPEDANCE +/- 10% * = diff.	DIELECTRIC THICKNESS
TOP LAYER	SIGNAL LAYER	0.12/0.12	35 um	≅100 Ohms	*=CRITICAL
LAYER 2	GND PLANE	-	35 um	-	≅0.1 mm
LAYER 3	POWER PLANE	-	35 um	-	1.3 mm
BOTTOM LAYER	SIGNAL LAYER	0.12/0.12	35 um	≅100 Ohms	≅0.1 mm
FINISHED BOARD THICKNESS +/-10%:					1.6 mm



Metric Drill Legend TOP to BOTTOM				
Drill sizes are considered finished.				
ALL UNITS ARE IN MILLIMETERS				
Figure	Dia.	Tol.	TYPE	QTY
+	0.30		PLATED	169
o	0.40		PLATED	175
o	0.70		PLATED	4
o	0.80		PLATED	12
△	0.85		PLATED	1
⊕	0.95	+0.05/-0.05	PLATED	9
o	1.00		PLATED	21
◇	1.05		PLATED	6
⊞	1.05	+0.05/-0.05	PLATED	10
△	2.50		PLATED	2
o	2.70		PLATED	4
◇	1.30		NON-PLATED	2
⊞	1.40		NON-PLATED	2

TOTAL HOLES: 417



EDA-02319-V3
 DESS P. VULLIEZ
 DATE 13/07/2012